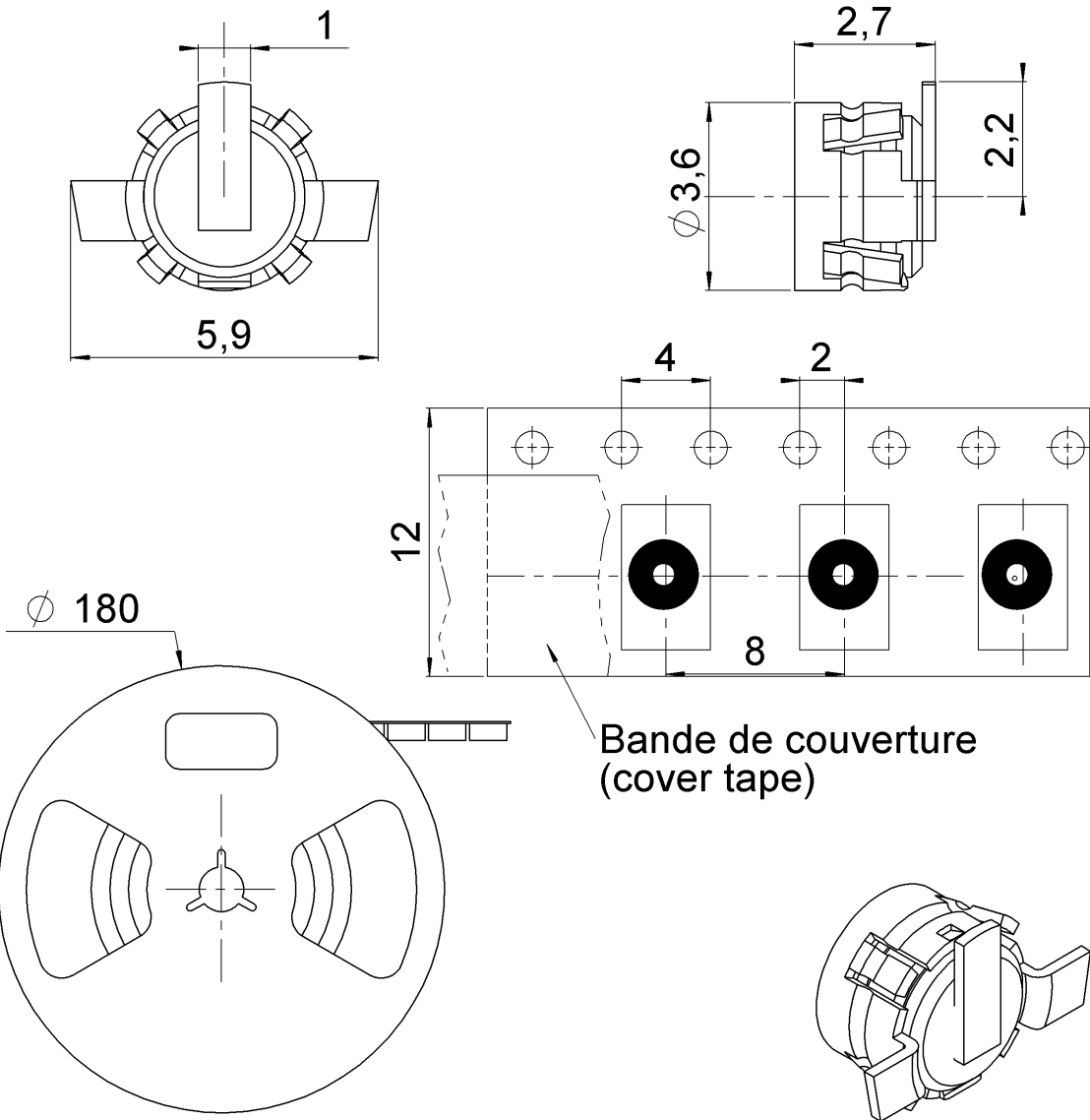
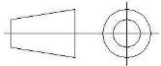


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All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (μm)
Body	PHOSPHOR BRONZE	GOLD 0.2 OVER NICKEL 2
Center contact	BRASS	GOLD 0.2 OVER NICKEL 2
Outer contact	PHOSPHOR BRONZE	GOLD 0.2 OVER NICKEL 2
Insulator	PTFE	
Gasket	-	-
Others parts	-	-
-	-	-
-	-	-

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SERIES MMT

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PACKAGING

Standard	Unit	Other
500	Contact us	Contact us

ELECTRICAL CHARACTERISTICS

Impedance	50	Ω
Frequency	0-8	GHz
VSWR	1.10 + 0,0500	x F(GHz) Maxi
Insertion loss	0.20	√F(GHz) dB Maxi
RF leakage	- (NA	- F(GHz)) dB Maxi
Voltage rating	170	Veff Maxi
Dielectric withstanding voltage	500	Veff mini
Insulation resistance	5000	MΩ mini

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating End	NA	N mini
Axial force – Opposite end	NA	N mini
Torque	NA	N.cm mini
Recommended torque		
Mating	NA	N.cm
Panel nut	NA	N.cm
Clamp nut	NA	N.cm
A/F clamp nut	0,0000	mm
Mating life	500	Cycles mini
Weight	0,1000	g

ENVIRONMENTAL

Operating temperature	-55/+100	°C
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

SPECIFICATIONCABLE ASSEMBLY

Stripping	a	b	c	d	e	f
mm	0	0	0	0	0	0

Assembly instruction:

Recommended cable(s)

Characteristics indicated on this data sheet are those that can be achieved with the highest performance cable. Intrinsic limitations of the cable may diminish the performance of the assembly

Cable retention

- pull off	NA	N mini
- torque	NA	N.cm

TOOLING

Part Number	Description	Hexagon
.	.	.

OTHER CHARACTERISTICS

accouplt : 18Nmax / desacc. : 7Nmin

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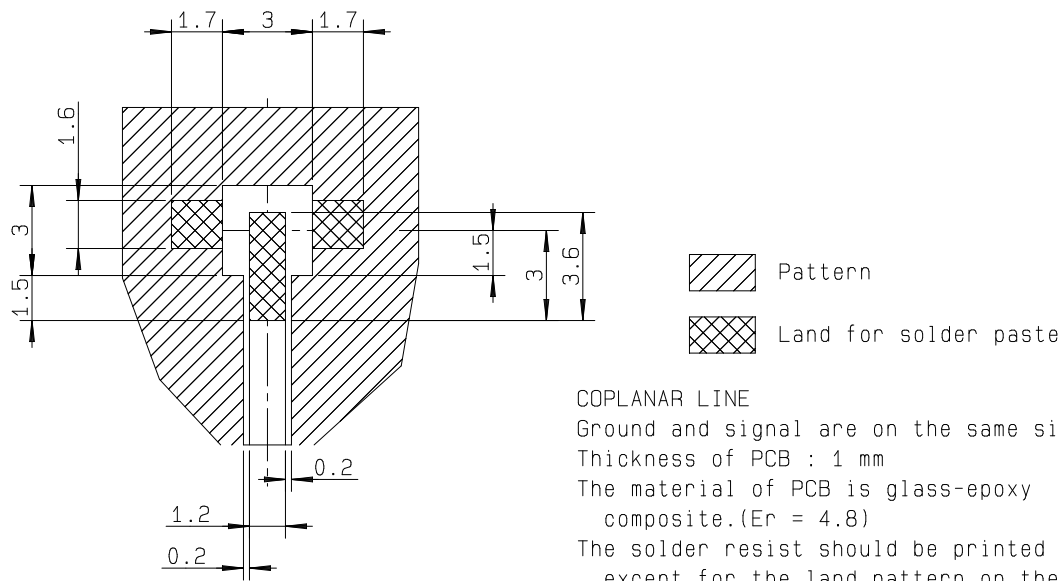
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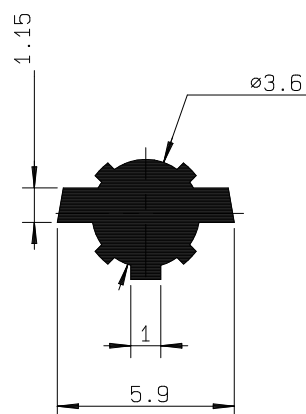
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MMT SERIES - INFORMATION

ALL DIMENSIONS IN MM



ALL DIMENSIONS IN MM

SHADOW OF MMT RECEPTACLE
FOR VIDEO CAMERA

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SERIES MMT

PART NUMBER R210408052

SOLDER PROCEDURE OF MMT RECEPTACLE**IN INDUSTRIAL ENVIRONMENT**

- 1 – Deposition of solder paste Sn Ag4 Cu0.5 on mounting zone by screen printing application.
We recommend a Low Residue Solid Flux.

We advise a thickness of 200 microns (7.800 microinches). Verify that the edges of the prined zone are clean.

- 2 – Placement of the receptacle on the mounting zone with an automatic machine of « pick and place » type.

A video camera is recommended for positioning of the component. (see page 3)

Adhesive agents must not be used on the receptacle.

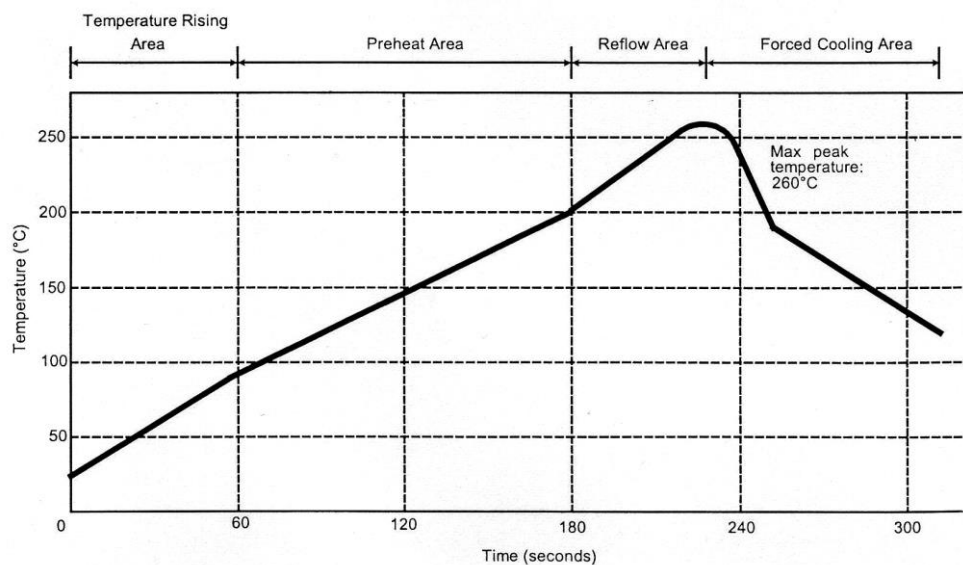
- 3 – Soldering by infra-red reflow.

Below, please find the typical profile to use.

- 4 – Cleaning of printed circuit boards

- 5 – Verification of solder joints and position of the component by visual inspection

Note : The MMT receptacle and the MMT plug must not be mated before completion of this procedure.



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec